

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	299	kimura near mutsumi.in.	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
2	BRS	L2	127	1 and (thin near film)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
3	BRS	L3	26	2 and (second near3 substrate)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
4	BRS	L4	55466	(short near3 side\$1)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Type	L #	Hits	Search Text	DBs
5	BRS	L5	62	(short near3 side\$1) near15 (second near3 substrate)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
6	BRS	L6	568	(curve\$3) near15 ((second) near3 (substrate or wafer))	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
7	BRS	L7	61	((curve\$3) near15 ((second) near3 (substrate or wafer))) near25 (element or chip or die or component or integrated near circuit)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
8	BRS	L8	27660	((second) near3 (substrate or wafer)) near25 (element or chip or die or component or integrated near circuit)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Type	L #	Hits	Search Text	DBs
9	BRS	L9	3593	(side\$1) near15 ((second) near3 (substrate or wafer)) near25 (element or chip or die or component or integrated near circuit)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
10	BRS	L10	26	(short\$3 near5 side\$1) near15 ((second) near3 (substrate or wafer)) near25 (element or chip or die or component or integrated near circuit)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
11	BRS	L11	20	(short\$3 near side\$1) near15 ((second) near3 (substrate or wafer)) near25 (element or chip or die or component or integrated near circuit)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
12	BRS	L12	2	(short\$3 near side\$1) near15 ((second) near3 (substrate or wafer)) near25 (curv\$5)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Type	L #	Hits	Search Text	DBs
13	BRS	L13	126	(side\$1) near15 ((second) near3 (substrate or wafer)) near25 (curv\$5)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
14	BRS	L14	881	((second) near3 (substrate or wafer)) near25 (curv\$5)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
15	BRS	L15	1169	((second) near3 (substrate or wafer)) near25 (concav\$5 or convex\$3)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
16	BRS	L16	127	((second) near3 (substrate or wafer)) near25 (concav\$5 or convex\$3)) near25 (element)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Type	L #	Hits	Search Text	DBs
17	BRS	L17	40	((second) near3 (substrate or wafer)) near25 (concav\$5 or convex\$3)) near25 (componen or chip)	US-PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TDB
18	BRS	L18	57	((second) near3 (substrate or wafer)) near25 (concav\$5 or convex\$3)) near25 (component or chip)	US-PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TDB
19	BRS	L19	25	((second) near3 (substrate or wafer)) near25 (concav\$5 or convex\$3)) near25 (die or integrated near circuit)	US-PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TDB

	U	1	Document ID	Title
1			US 20050023960 A1	Electroluminescence panel and manufacturing process therefor
2			US 20030107123 A1	Memory device power distribution in memory assemblies
3			US 20020056911 A1	Semiconductor device
4			US 20020053732 A1	Semiconductor device
5			US 20020043719 A1	Semiconductor device
6			US 20020024473 A1	Low profile, high gain frequency tunable variable impedance transmission line loaded antenna
7			US 6617196 B2	Semiconductor device
8			US 6507384 B1	Flexible printed wiring board, electro-optical device, and electronic equipment
9			US 6489925 B2	Low profile, high gain frequency tunable variable impedance transmission line loaded antenna

	U	1	Document ID	Title
10			US 6452266 B1	Semiconductor device
11			US 6411359 B1	Liquid crystal display device having smaller frame area
12			US 6388318 B1	Surface mount-type package of ball grid array with multi-chip mounting
13			US 4019049 A	Photoelectric transducing unit and system for detecting the sharpness of the image of object by means of the unit
14			US 3961178 A	Image sharpness detecting system and apparatus utilizing the same
15			JP 2004235238 A	PROCESS FOR FABRICATING THIN FILM ELEMENT, THIN FILM TRANSISTOR CIRCUIT, ACTIVE MATRIX DISPLAY, ELECTRO-OPTICAL DEVICE, AND ELECTRONIC EQUIPMENT
16			JP 2003332101 A	RESISTOR
17	X		JP 2002311447 A	LIQUID CRYSTAL DISPLAY
18	X		JP 2000349402 A	FLEXIBLE PRINTED WIRING BOARD, OPTOELECTRONIC DEVICE AND ELECTRONIC APPARATUS
19	X		JP 2000349401 A	FLEXIBLE PRINTED WIRING BOARD, OPTOELECTRONIC DEVICE AND ELECTRONIC APPARATUS
20	X		EP 1039788 A2	Flexible printed wiring board, electro-optical device, and electronic equipment